

# SURFACE MOUNT GENERAL PURPOSE SILICON RECTIFIERS

Forward Current-1.0A

Reverse Voltage-50V to 1000V

#### FEATURES

- For surface mount applications
- Glass passivated chip junction
- Low profile package
- ♦ ESD (HBM) > 4KV
- Lead free in comply with EU RoHS 2011/65/EU directives

### **MECHANICAL DATA**

- Case: SMA molded plastic body
- Terminals: Solderable per MIL-STD-750, Method 2026
- Weight: Approximated 0.055 grams

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derating by 20 %.

PARAMETER	SYMBOL	M1	M2	М3	M4	M5	M6	M7	UNIT
Maximum Repetitive Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	IF(AV)				1.0				Α
Peak Forward Surge Current (Note1)	IFSM	30						Α	
Maximum Forward Voltage at 1.0 A	VF	1.1					V		
Maximum DC Reverse Current at Rated DC Blocking Voltage T <sub>A</sub> =25°C T <sub>A</sub> =125°C	IR	5 50					μA		
Typical Junction Capacitance (Note2)		15						pF	
Typical Thermal Resistance (Note3)	R <sub>θJA</sub>	75						°C/W	
Operating and Storage Temperature Range	TJ,TSTG	-55 to +150						°C	

Notes: 1. Measured at 8.3 ms single half sine wave superimposed on rated load (JEDEC Method).

2. Measured at 1MHz and applied reverse voltage of 4 V D.C.

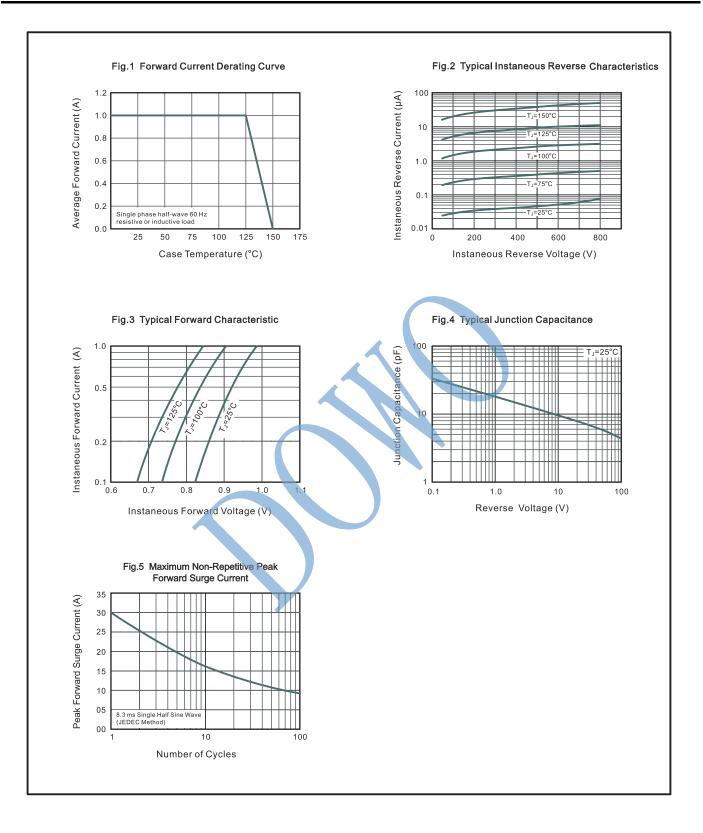
3. P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.

PINNING	
PIN	DESCRIPTION
1	Cathode
2	Anode





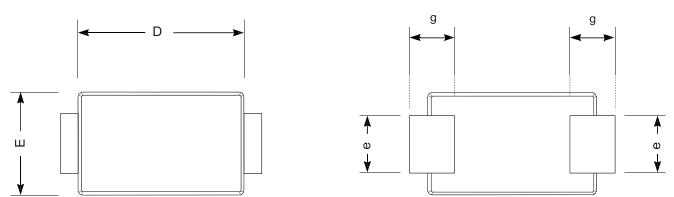
## **RATINGS AND CHARACTERISTIC CURVES**

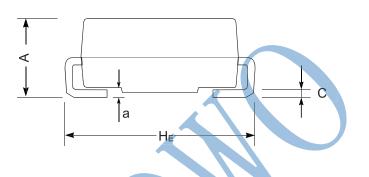




## PACKAGE OUTLINE







UNIT		А	D	E	HE	С	е	g	а
	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.0
mm	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	0.3
	max	87	181	106	205	12	63	59	40
mil	min	75	157	91	185	6	51	35	12

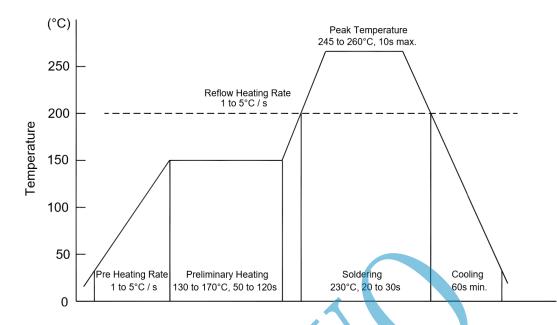
## **ORDERING INFORMATION**

Device	Package	Shipping			
M1 thru M7	SMA	5,000/Tape & Reel (13 inches)			



### CONDITIONS OF SOLDERING AND STORAGE

#### ■ RECOMMENDED CONDITIONS OF REFLOW SOLDERING



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer).
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

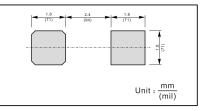
#### Condition of hand soldering

- Temperature: 370 °C
- Time: 3s max.
- Times: one time
- STORAGE CONDITIONS
  - Temperature
    5 to 40 °C
- Humidity
  30 to 80% RH
- Recommended period One yaer after manufacturing
- MSL
  - 1 Level

#### Marking

Type number	Marking code
M1	M1
M2	M2
M3	М3
M4	M4
M5	M5
M6	M6
M7	M7

#### Pad size



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